501889627 04/16/2012

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hung-Chun Wang	04/13/2012
Ming-Hui Chih	04/13/2012
Cheng Kun Tsai	04/13/2012
Wen-Chun Huang	04/13/2012
Ru-Gun Liu	04/13/2012

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13447857

CORRESPONDENCE DATA

Fax Number: (214)200-0853 Phone: 214-651-5000

Email: linda.ingram@haynesboone.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US

Mail.

Correspondent Name: HAYNES AND BOONE, LLP IP Section

Address Line 1: 2323 Victory Avenue

Address Line 2: Suite 700

Address Line 4: Dallas, TEXAS 75219

ATTORNEY DOCKET NUMBER: 24061.2131

NAME OF SUBMITTER: Rachel L.I. Davis

Total Attachments: 3

source=2131Assignment#page1.tif source=2131Assignment#page2.tif source=2131Assignment#page3.tif

REEL: 028052 FRAME: 0927

IOP \$40.00 13447857

501889627

Docket No.: 2012-0127 / 24061.2131

Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1)	Hung-Chun Wang	of	390, Chung-San Road, Ching-Shuei Taichung, Taiwan R.O.C.
(2)	Ming-Hui Chih	of	4F., No. 94, Lane 185, Zhongzheng Road Luzhou City, Taipei County 247 Taiwan R.O.C.
(3)	Cheng KunTsai	of	14F-1, No. 10, Lane 107, Kesyueyuan Rd., Hsinchu City 300, Taiwan R.O.C.
(4)	Wen-Chun Huang	of	No. 58, Zhong-Shan Road, Xi-Gang Xi-Gang District, Tainan City Taiwan 723, R.O.C.
(5)	Ru-Gun Liu	of	No.90, Chenggong 5th Street Zhubei City, Hsinchu County 302, Taiwan R.O.C.

have invented certain improvements in

PATTERN CORRECTION WITH LOCATION EFFECT

for which we have filed an application for Letters Patent of the United States of America on April 16, 2012, and assigned application number 13/447,857; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize

R-303116_1.DOC - 1 -

Docket No.: 2012-1027 / 24061.2131

Customer No.: 000042717

and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor	Mamai
mvemor	ivaine:

Hung-Chun Wang

Residence Address:

390, Chung-San Road, Ching-Shuei

Taichung, Taiwan R.O.C.

Dated: 2012/4/13

Inventor Signature

Inventor Name:

Ming-Hui Chih

Residence Address:

4F., No. 94, Lane 185, Zhongzheng Road

Luzhou City, Taipei County 247

Taiwan R.O.C.

Dated: Min 2017,04,13

Inventor Signature

-2-

Docket No.: 2012-1027 / 24061.2131

Customer No.: 000042717

Inventor Name:

Cheng KunTsai

Residence Address:

14F-1, No. 10, Lane 107, Kesyueyuan Rd.,

Hsinchu City 300, Taiwan R.O.C.

Dated: 2012, 04, 13

Cheng Kun Tsai Inventor Signature

Inventor Name:

Wen-Chun Huang

Residence Address:

No. 58, Zhong-Shan Road, Xi-Gang

Xi-Gang District, Tainan City, Taiwan 723, R.O.C.

Dated: 04/13/2012

Inventor Signature

Inventor Name:

Ru-Gun Liu

Residence Address:

No.90, Chenggong 5th Street

Zhubei City, Hsinchu County 302, Taiwan R.O.C.

Dasad.

13. 2012

Pu - (· un 2 · u

Inventor Signature

- 3 -

D-2131 - Assignment.doc

RECORDED: 04/16/2012